



EtraLED-LUN-11080 Luminus Modular Passive Star Heat Sink Φ

Features VS Benefits

- * The EtraLED-LUN-11080 Luminus Passive Star LED Heat Sinks are specifically designed for luminaires using the Luminus LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 3000 to 7,200 lumen.
- * Thermal resistance range Rth 1.03°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Luminus COB series.
- * Diameter 110mm standard height 80mm, Other heights on request.
- * Forged from highly conductive aluminum.

Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Luminus COB's and LED modules which standard fit on the srar LED heat sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.







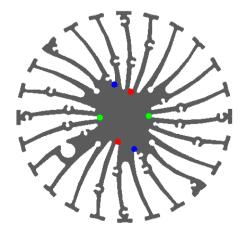














CIM/ CLM/CXM-9 -AC;

TE Connectivity Holder: 2213678-5; BJB Holder:47.319.6060.50;

Direct mounting with machine screws M3x6.5mm

Luminus COB series.

Direct mounting with machine screws M3x6.5mm.

Lena series: CN12xxx; Lenina series: CN12xxx; C12xxx;





Mounting Options and Drawings & Dimensions

Example: EtraLED-LUN-11080-B-1,2

Example:EtraLED-LUN-110 1 - 2

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1 Height (mm)

Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

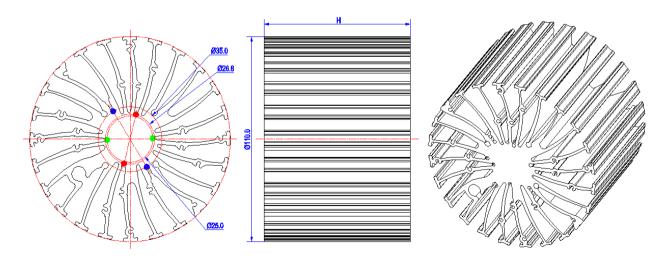
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means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
			Lenina Series	Lena series	INCEAD	DEPTH	DISTANCE
1	CXM-6-AC; CIM/ CLM/CXM-9 -AC;	BJB Holder 47.319.6060.50	CN14xxx; C12xxx;	CN14xxx; C12xxx;	М3	6.5mm	25.0mm/ 2-@180° (Zhaga book 11)
		TE Holder 2213678-5					
2	CXM-11; CIM/CLM/CXM-14	/	CN12xxx; C12xxx;	CN12xxx;	М3	6.5mm	26.8mm/ 2-@180°
3		BJB Holder 47.319.2021.50			МЗ	6.5mm	35.0mm/ 2-@180° (Zhaga book 3)
		TE Holder 2213254-1					

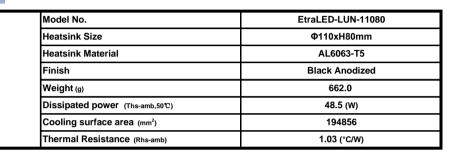






The product deta table

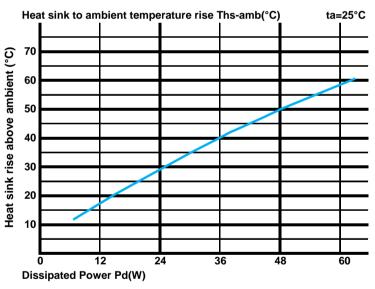
EtraLED



The thermal data table

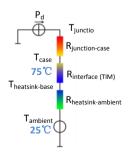
- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (I \eta L)$.
 - Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)		
		EtraLED-LUN-11080			
Dissipated Power Pd(W)	12.0	1.33	16.0		
	24.0	1.21	29.0		
	36.0	1.11	40.0		
	48.0	1.03	49.5		
	60.0	0.95	57.0		



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:module} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$

 $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.1-0.15 mm\ is\ recommended.$



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- θ Thermal Resistance [°C/M]; Ths Heatsink temperature; Ta Ambient temperature;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface}(TIM)$ ["C,M"], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ ["C,M"], and the ambient temperature is $T_{ambient}$ ["C].
- *Thermal resistances outside the package $R_{Interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{iunction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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